\$ \$40 OO 12299

PATENT ASSIGNMENT

Electronic Version v1.1 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Shuji HAHAKURA	07/09/2008
Kazuya OHMATSU	07/09/2008
Munetsugu UEYAMA	07/09/2008
Katsuya HASEGAWA	07/09/2008

RECEIVING PARTY DATA

Name:	Sumitomo Electric Industries, Ltd.	
Street Address:	5-33, Kitahama 4-chome, Chuo-ku	
City:	Osaka-shi, Osaka	
State/Country:	JAPAN	
Postal Code:	541-0041	

Name:	International Superconductivity Technology Center, the Juridical Foundation	
Street Address:	10-13, Shinonome 1-chome, Koto-ku	
City:	Tokyo	
State/Country:	JAPAN	
Postal Code:	135-0062	

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	12299141

CORRESPONDENCE DATA

Fax Number: (202)204-0289

Correspondence will be sent via US Mail when the fax attempt is unsuccessful.

Phone: 202-842-8800

Email: faiza.shahzadi@dbr.com

Correspondent Name: DRINKER BIDDLE & REATH (DC)

Address Line 1: 1500 K STREET, N.W.

PATENT

REEL: 021767 FRAME: 0842

500691848

Address Line 2: SUITE 1100
Address Line 4: WASHINGTON, DISTRICT OF COLUMBIA 20005-1209

ATTORNEY DOCKET NUMBER: 201917_0014_430969

NAME OF SUBMITTER: Peter J. Sistare

Total Attachments: 2
source=201917_0014_430969_Assignment#page1.tif
source=201917_0014_430969_Assignment#page2.tif

PATENT REEL: 021767 FRAME: 0843

ATTORNEY DOCKET NO.:

SOLE/JOINT INVENTION (U.S. Rights Only)

ASSIGNMENT

WHEREAS I/We, the below named inventor(s), [hereinafter referred to as Assignor(s)], have

made an invention entitled: Superconducting Thin Film Material and Method of Manufacturing the Same				
for which I/WE executed an application for United States Letters Patent concurrently herewith; or filed an application for United States Letters Patent on, (Serial No); and				
WHEREAS, (1) Sumitomo Electric Industries, Ltd., and (2) International Superconductivity Technology Center, the Juridical Foundation, a corporation of Japan, whose post office address is (1) 5-33, Kitahama 4-chome, Chuo-ku, Osaka-shi, Osaka 541-0041 Japan, and (2) 10-13, Shinonome 1-chome, Koto-ku, Tokyo 135-0062 Japan, (hereinafter referred to as Assignee), is desirous of securing the entire right, title, and interest in and to this invention, the application for United States Letters Patent on this invention and the Letters Patent to issue upon this application;				
NOW THEREFORE, be it known that from assignee is hereby acknowledged, I/WE, and do hereby sell, assign, transfer, and set ov MY/OUR entire right, title, and interest in and continuations thereof, and all Letters Patent or reissues thereof; and I/WE hereby authorize a the United States to issue all Letters Patent for accordance with the terms of this Assignment	rer unto the assignee, its lawful successors of the to this invention and this application, and the United States which may be granted and request the Commissioner of Patents are this invention to assignee, its successors	ferred, and set over, s and assigns, d all divisions, and thereon, and all and Trademarks of		
AND, I/WE HEREBY further covena communicate with assignee, its successors and invention and testify in any legal proceeding, and deliver all papers that may be necessary of assignee, its successors and assigns, execute a all rightful oaths and generally do everything and enforce proper patent protection for this is expense incident to the execution of such papers.	sign all lawful papers when called upon to or desirable to perfect the title to this inver- all divisional, continuation, and reissue ap- possible to aid assignee, its successors and invention in the United States, it being und	pecting this o do so, execute ntion in said plications, make d assigns, to obtain derstood that any		
AND, I/WE HEREBY authorize and and Power of Attorney in this application, to i) the filing date and application number IN TESTIMONY WHEREOF, I/WE	er of said application when known.	red in the Declaration, filed		
Full Name of Sole or First Assignor Shuji HAHAKURA	Assignor's Signature Shuji Hahakura	Date July 9, 2008		
Address c/o Osaka Works of Sumittd., 1-3, Shimaya 1-chome, Ko 554-0024 Japan	tomo Electric Industries,	Citizenship Japanese		
Full Name of Second Assignor Kazuya OHMATSU	Assignor's Signature Huguya Ohmotau	Date July 9, 2008		
Address c/o Osaka Works of Sumit Ltd., 1-3, Shimaya 1-chome, Ko 554-0024 Japan	nohana-ku, Osaka-shi, Osaka	Citizenship Japanese		
Names of additional inventors attached Ye	es No	\$		

PATENT REEL: 021767 FRAME: 0844

ATTORNEY DOCKET NO.:

Full Name of Third Assignor Munetsugu UEYAMA	Assignor's Signature	Date July 9, 2008
Munetsugu UEYAMA Address c/o Osaka Works of Sumitomo E chome, Konohana-ku, Osaka-shi, Osaka 554	Citizenship Japanese	
Full Name of Fourth Assignor Katsuya HASEGAWA	Assignor's Signature Katsuya Hasegawa	Date July 9, 2008
Address c/o Osaka Works of Sumitomo Electric Industries, Ltd., 1-3, Shimaya 1-chome, Konohana-ku, Osaka-shi, Osaka 554-0024 Japan		Citizenship Japanese
Full Name of Fifth Assignor	Assignor's Signature	Date
Address		Citizenship
Full Name of Sixth Assignor	Assignor's Signature	Date
Address		Citizenship
Full Name of Seventh Assignor	Assignor's Signature	Date
Address		Citizenship
Full Name of Eighth Assignor	Assignor's Signature	Date
Address		Citizenship
Full Name of Ninth Assignor	Assignor's Signature	Date
Address		Citizenship
Full Name of Tenth Assignor	Assignor's Signature	Date
Address	I	Citizenship
Full Name of Eleventh Assignor	Assignor's Signature	Date
Address	, , , , , , , , , , , , , , , , , , , 	Citizenship
Names of additional inventors attached \(\square\)	Yes 🛮 No	

PATENT REEL: 021767 FRAME: 0845